

We Claim:

1. A method of securing a multi-dimensionally constructed chip stack, the method which comprises:

providing a chip stack having a plurality of part chips connected to one another at respective contact areas, at least one of the part chips including functional components;

providing respective conductor tracks in the part chips;

providing feed-through contacts at the respective contact areas for interconnecting the conductor tracks in the part chips such that that a continuous electrical signal path running through the part chips is formed;

transmitting an electrical signal from a transmitting device provided at a first end of the continuous electrical signal path to a receiving device provided at a second end of the continuous electrical signal path;

providing a continuous electrical reference signal path running from the transmitting device to the receiving device;

transmitting an electrical reference signal over the continuous electrical reference signal path at the same time as the electrical signal is transmitted; and









said securing device further including a transmitting device provided at said first end of said continuous electrical signal path, a receiving device provided at said second end of said continuous electrical signal path, said receiving device being configured to receive an electrical signal transmitted via said continuous electrical signal path, a continuous electrical reference signal path extending from said transmitting device to said receiving device, and a determining device operatively connected to said receiving device, said determining device determining that there is a



